



Interconnect Crosstalk Analysis in Sub-powered Integrated Circuits

Alexandru Amaricai

Oana Boncalo

Sergiu Nimara





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Outline

- Motivation & Goal
- Introduction in interconnects
- Interconnect modeling
- SPICE simulations
- Conclusions

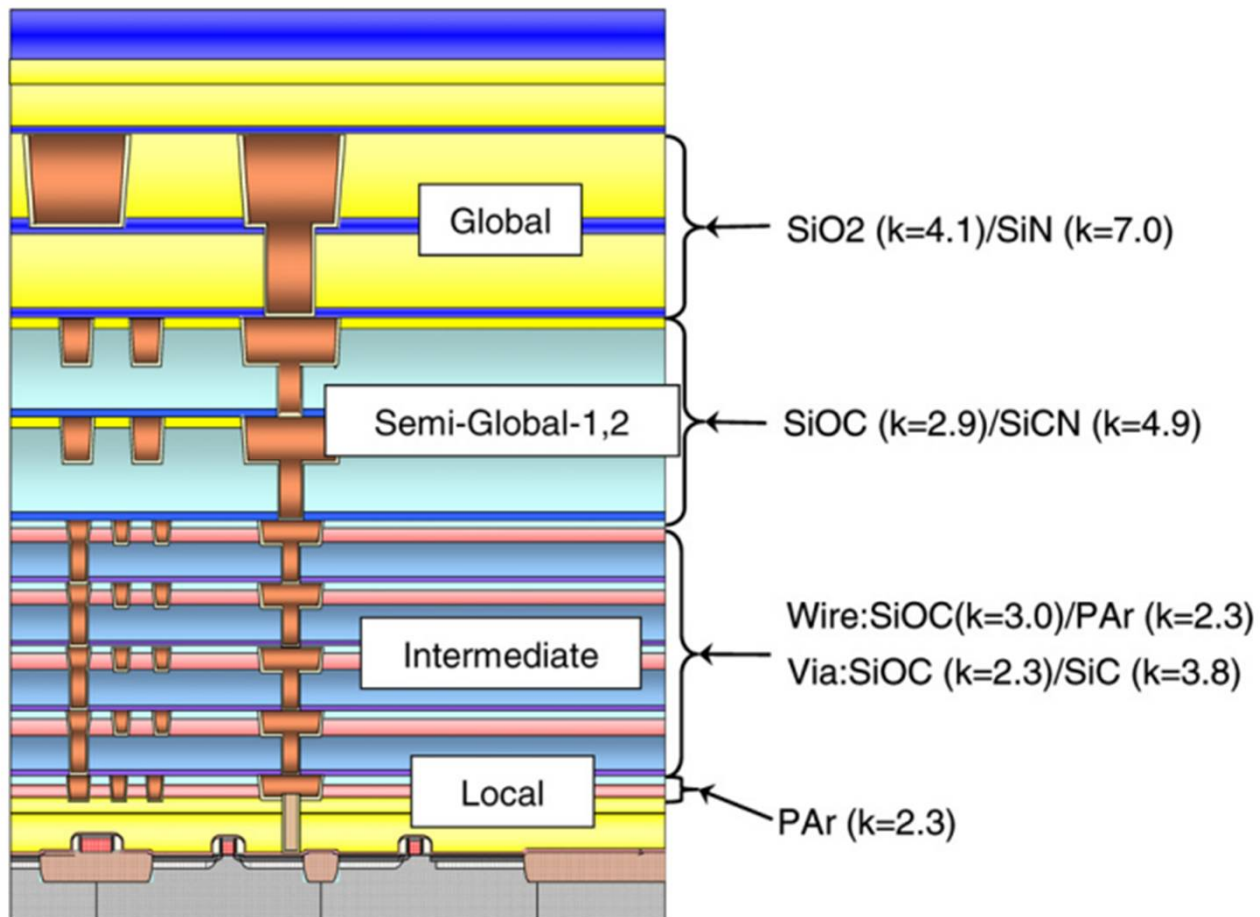
Motivation & Goals

- Determine data dependence error models for interconnects
 - Logic level alteration
 - Delay dependent error models
- Establish design guidelines for interconnects
 - Determine wire spacing & length
 - Parameters:
 - Supply voltage (range)
 - Dielectric material
 - Maximum number of accepted errors

Goals

- Determine the minimum spacing
 - Larger spacing -> greater cost
 - Increase number of wires on plane
 - Very large transports
- Determine the maximum length
 - Reduction of repeater buffers for long interconnects
 - Reduction of silicon usage
 - Reduction of metallic vias

Introduction in interconnect



$$R = \frac{\rho \cdot l}{w \cdot t}$$

Interconnect electrical properties

- Resistance

- Depends on physical characteristics
- Timing parameters of a wire
- Power consumption characteristics of a wire

$$R = \rho * \frac{l}{S}$$

- Inductance

- Self inductance
 - Depends on the length & perimeter
 - Voltage increase/decrease when switching

$$L_s = \mu_0 * \frac{l}{2\Pi} \left[\ln\left(\frac{2l}{p}\right) + \frac{1}{2} + 0.22 * \frac{p}{l} \right]$$

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Interconnect electrical properties

- Inductance

- Mutual inductance
 - Inductive cross-coupling
 - Wide range affect (spans multi-wires)
 - Depends on the wire spacing and length

$$M = \mu_0 * \frac{l}{2\Pi} \left[\ln\left(\frac{2l}{d}\right) - 1 + \frac{d}{l} \right]$$

- Capacitance

- Ground capacitance
 - Depends on wire spacing & dielectric material

$$C_g = \varepsilon \left[\frac{w}{h} + 2.04 * \left(\frac{s}{s + 0.54 * h} \right)^{1.77} \right]$$

- Cross-coupled capacitance
 - Neighbor wires affected

$$C_c = \varepsilon \left[1.41 * \frac{t}{s} * e^{-\frac{4s}{s+8.01h}} + 2.37 * \left(\frac{w}{w+0.31s} \right)^{0.28} * \left(\frac{h}{h+8.91s} \right)^{0.76} * e^{-\frac{2s}{s+6h}} \right]$$

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Noise sources in interconnects

- Crosstalk
 - Inductance/Capacitance crosstalk
 - Substrate crosstalk
 - Passive components in substrate
 - Power/ground line crosstalk
- Transmission line effects
 - Affects long lines (global)
 - Depends on the signal frequency
 - Due to impedance discontinuities
 - Vias, wire bends, cross-over lines, etc
 - Process defects (bubbles, diffusion, etc)
- Electro-magnetic interference

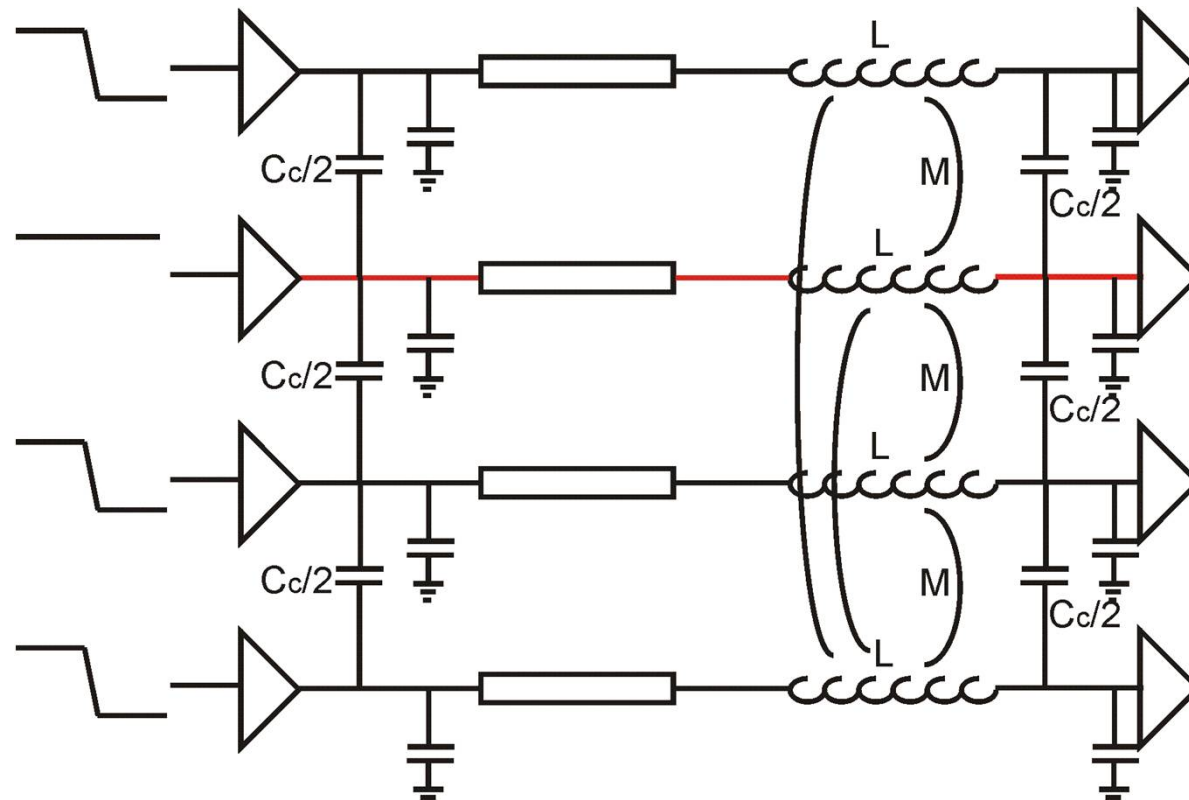
Interconnect modeling

- RC models
 - Inductors' influence is around 5%
 - Pi model of the wire
- RLC models
 - Include inductors
 - Second degree differential equations
- RLCG models
 - Include very large resistor between wires
 - Conductance through the dielectric material.

Simulation scenario

- 4-wire interconnect RLC model
- 4 driver buffers & 4 receiver buffers
- Victim line – internal wire
- 560 simulations
- Parameters:
 - Spacing
 - Length
 - Dielectric constant
 - Vdd

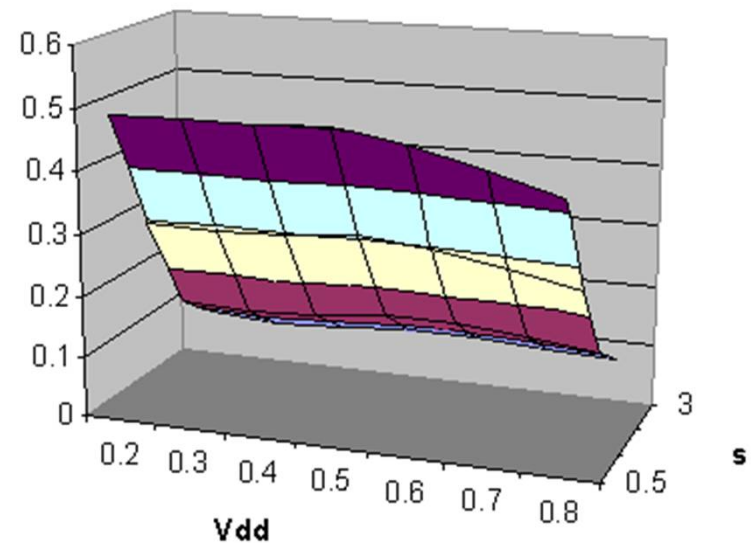
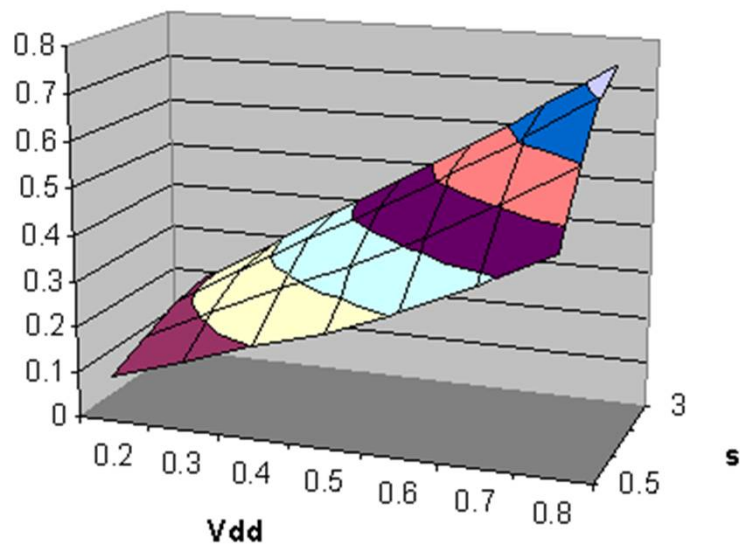
Simulation scenario



Simulation results

Dependence on spacing

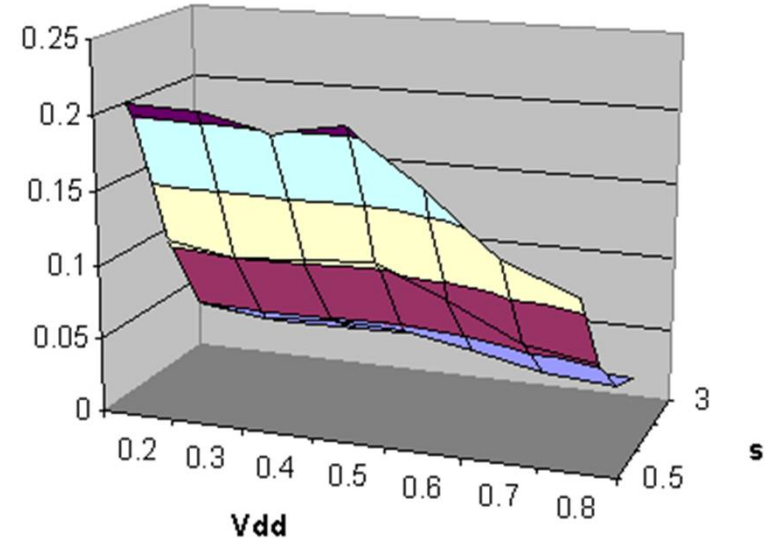
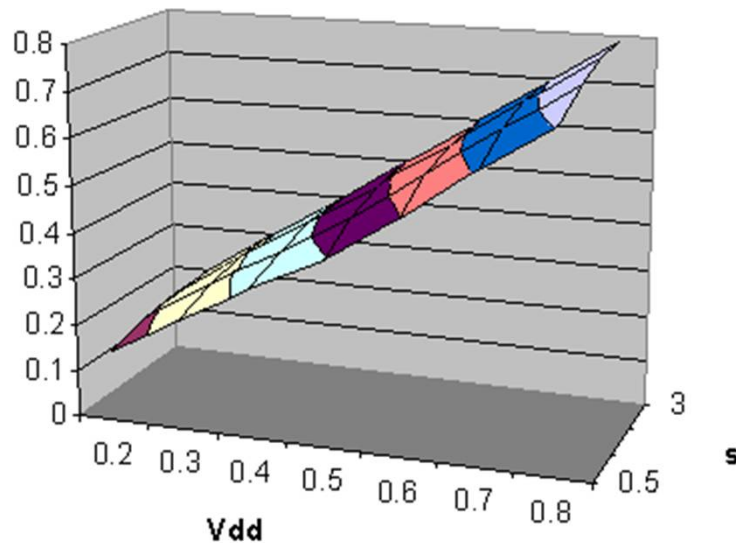
- $L=100 \text{ um}$ $k = 3$



Simulation results

Dependence on spacing

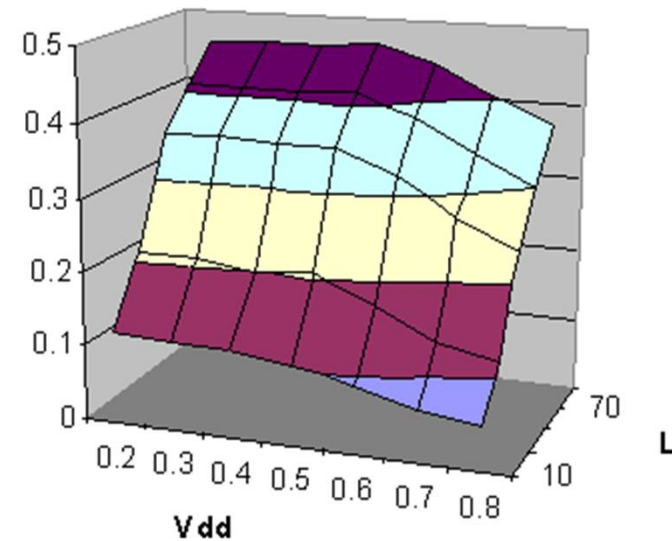
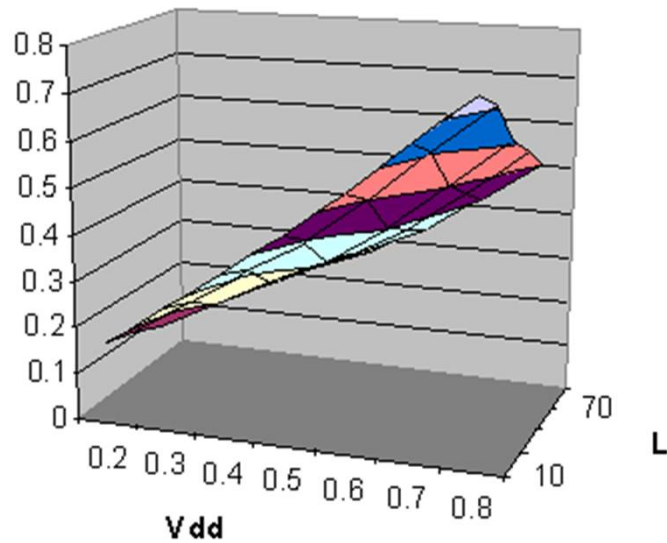
- $L = 20 \text{ um}$ $k = 2.2$



Simulation results

Dependence on length

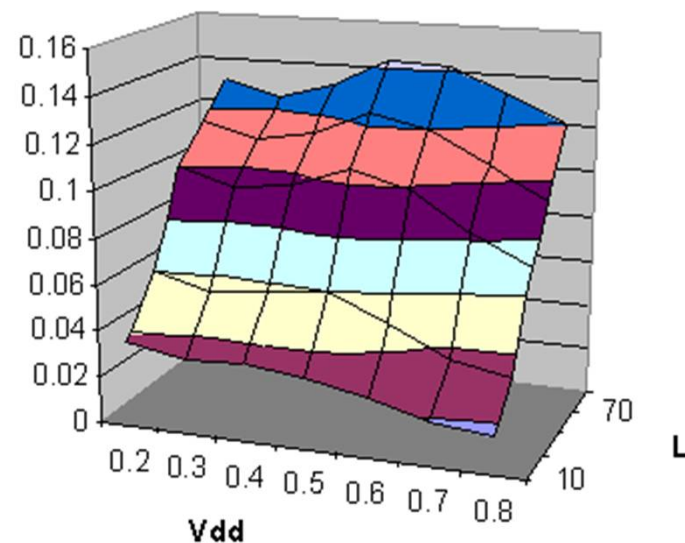
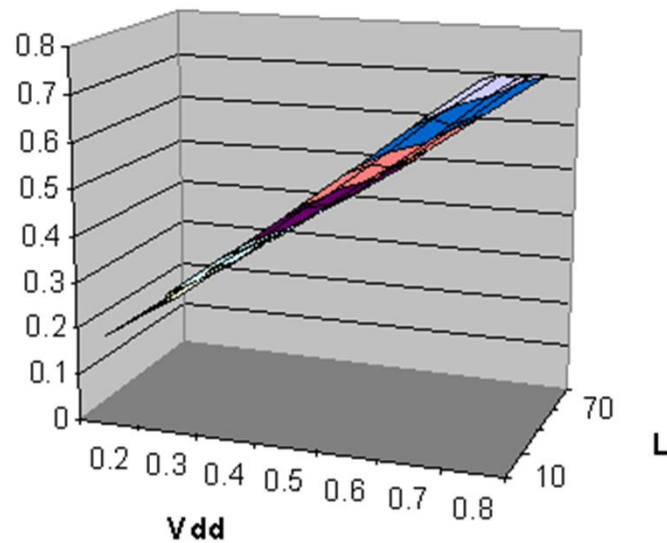
- $k = 2.2$ $s = 0.5$



Simulation results

Dependence on length

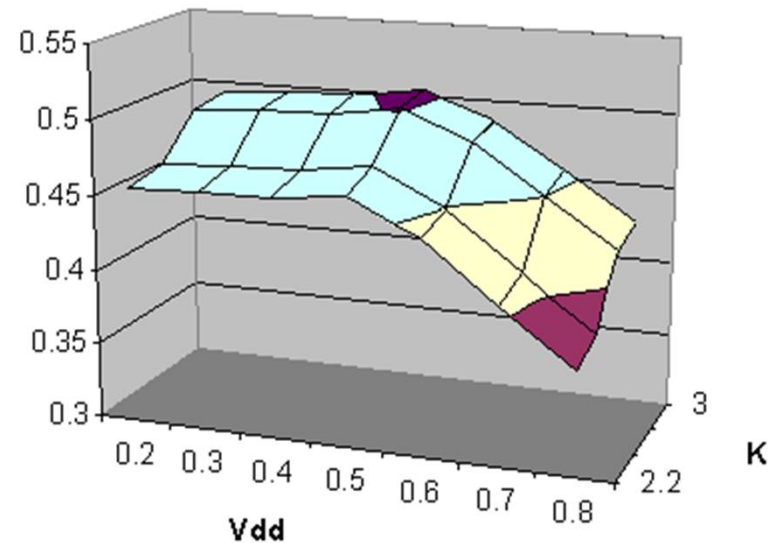
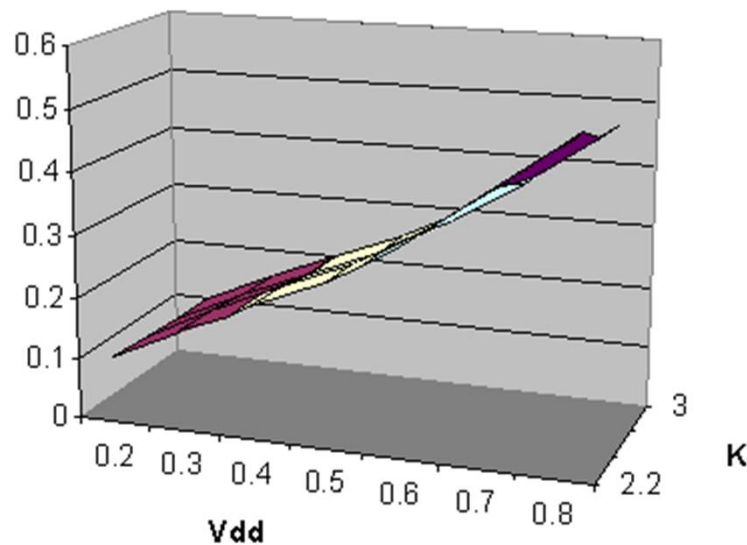
- $k = 3$ $s = 2$



Simulation results

Dependence on dielectric constant

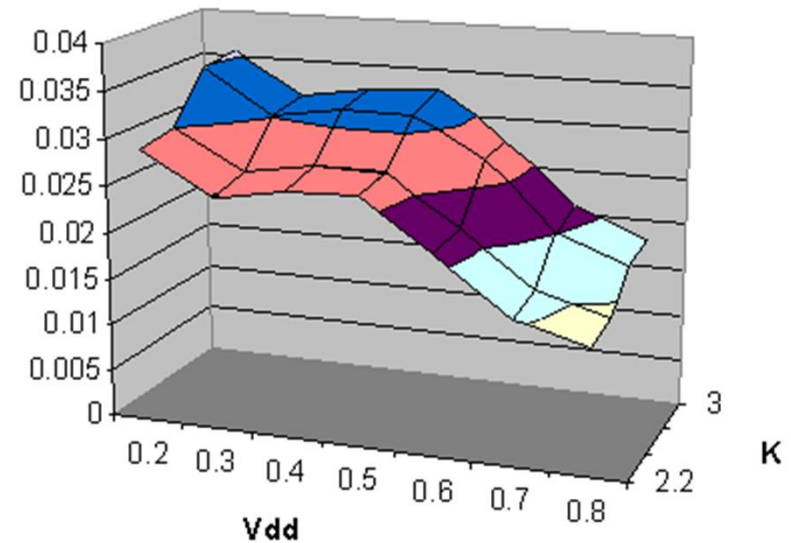
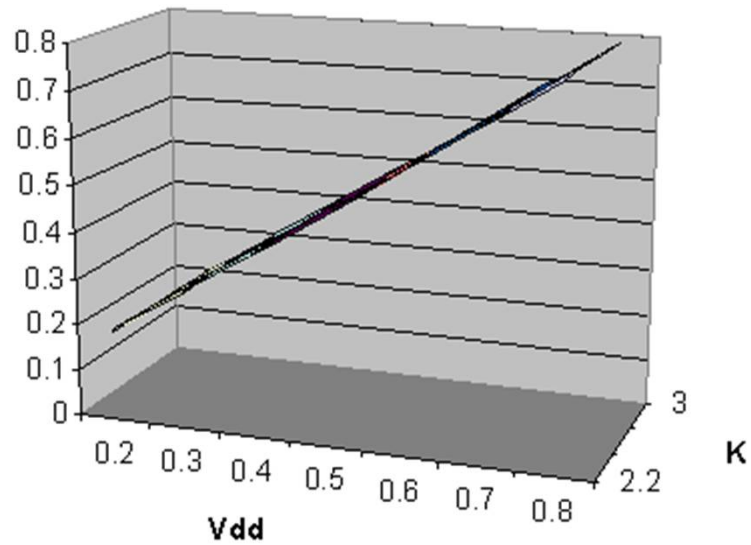
$L = 100 \text{ } \mu\text{m}$ $s = 0.5 \text{ } \mu\text{m}$



Simulation results

Dependence on dielectric constant

- $L=20\text{ }\mu\text{m}$ $s = 3\text{ }\mu\text{m}$



Conclusions

- Investigate the crosstalk effects in low supply voltage regions of operations
- Investigate the influence of different parameters (length, spacing, dielectric material)
- Logic level drop – small differences with respect to supply voltage
 - Maximum at around 0.5 V



Thank you

